

V

900

 $I_D$ 

## N-Channel Super Junction Power MOSFET II

#### **General Description**

The series of devices use advanced super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

#### Features

- •New technology for high voltage device
- •Low on-resistance and low conduction losses
- Small package
- Olltra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### Application

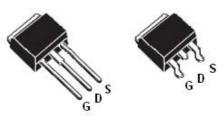
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

Daakaga	Marking	And	Ordoring	Information
Package	warking	Ana	Ordering	Information

Device	Device Package	Marking	
NCE90R1K2I	TO-251	NCE90R1K2I	
NCE90R1K2K	TO-252	NCE90R1K2K	

# $V_{\text{DS}}$ 1000 mΩ RDS(ON) TYP 5 А D С GO s

#### Schematic diagram



TO-251

TO-252

### Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGs=0V)	Vds	900	V
Gate-Source Voltage (VDs=0V)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	5	A
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	3	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	15	А
Maximum Power Dissipation(Tc=25°C)	PD	81	W
Derate above 25°C		0.65	W/°C
Single pulse avalanche energy (Note 2)	Eas	140	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	2.5	A
Repetitive Avalanche energy , $t_{\text{AR}}$ limited by $T_{j\text{max}}$ (Note 1)	E <sub>AR</sub>	0.4	mJ



## NCE90R1K2I,NCE90R1K2K

Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leqslant$ 480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leqslant 480 V, I_{SD} < I_D$	dv/dt	5	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55+150	°C

\* limited by maximum junction temperature

#### Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	1.54	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

#### Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Мах	Unit
On/off states			•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	900			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =900V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I <sub>DSS</sub>	V <sub>DS</sub> =900V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2.5A		1000	1200	mΩ
Dynamic Characteristics			•			
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> = 20V, I <sub>D</sub> = 2.5A		5.5		S
Input Capacitance	C <sub>lss</sub>			680		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		55		pF
Reverse Transfer Capacitance	Crss	F=1.0MHz		3.5		pF
Total Gate Charge	Qg			14.5	22	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =480V,I <sub>D</sub> =5A,		2.8		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V		5.5		nC
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		2		Ω
Switching times	·					
Turn-on Delay Time	t <sub>d(on)</sub>			7		nS
Turn-on Rise Time	tr	V <sub>DD</sub> =480V,I <sub>D</sub> =2.5A,		5		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =15Ω,V <sub>GS</sub> =10V		70	85	nS
Turn-Off Fall Time	t <sub>f</sub>			9	15	nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I <sub>SD</sub>	T -05%0			5	А
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			15	А
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =5A,V <sub>GS</sub> =0V		0.85	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			240		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =5A,di/dt=100A/µs		2.2		uC
Peak Reverse Recovery Current	Irrm			16		А

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^\circ\!\!\!\mathrm{C}$  ,VDD=50V,VG=10V, R\_G=25 $\!\Omega$ 



### **TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)**

#### Figure1. Safe operating area

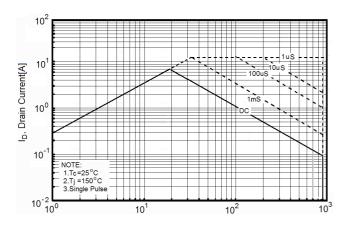


Figure3. Output characteristics

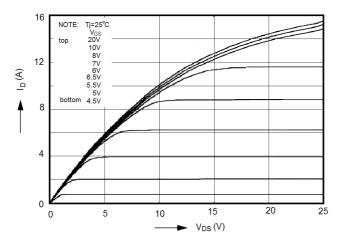
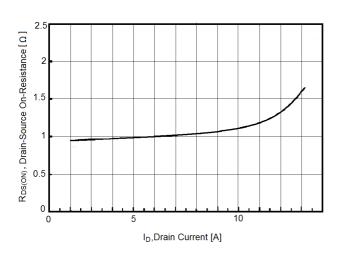


Figure5. Static drain-source on resistance



### Figure2. Source-Drain Diode Forward Voltage

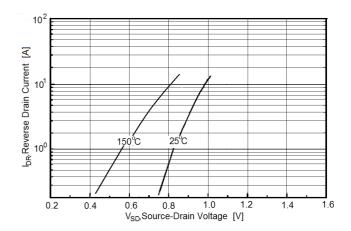


Figure4. Transfer characteristics

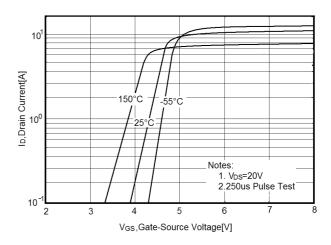


Figure6. R<sub>DS(ON)</sub> vs Junction Temperature

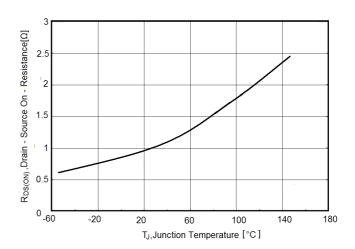




Figure7. BV<sub>DSS</sub> vs Junction Temperature

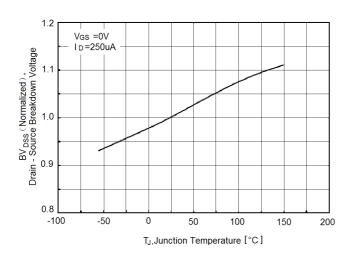


Figure9. Gate charge waveforms

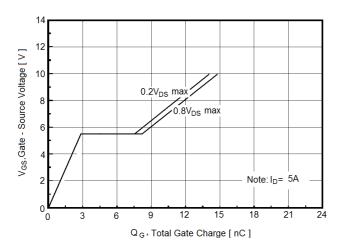


Figure11. Transient Thermal Impedance

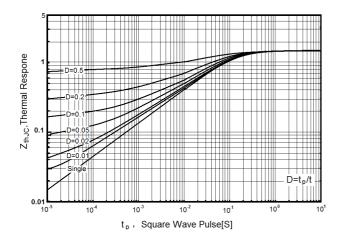
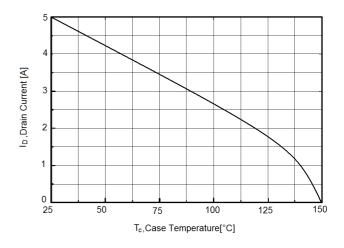
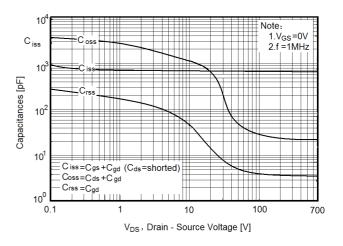


Figure8. Maximum  $I_D$  vs Junction Temperature



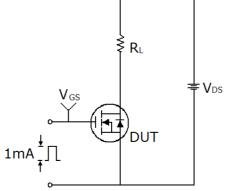


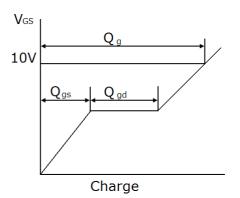




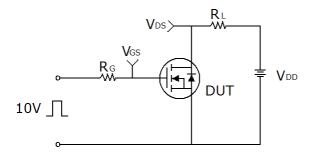
### Test circuit

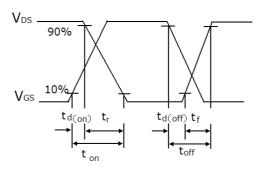
1) Gate charge test circuit & Waveform



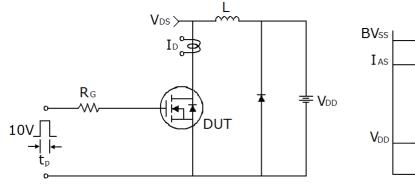


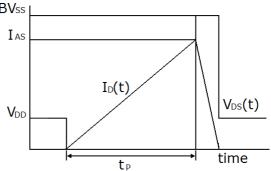
2) Switch Time Test Circuit:





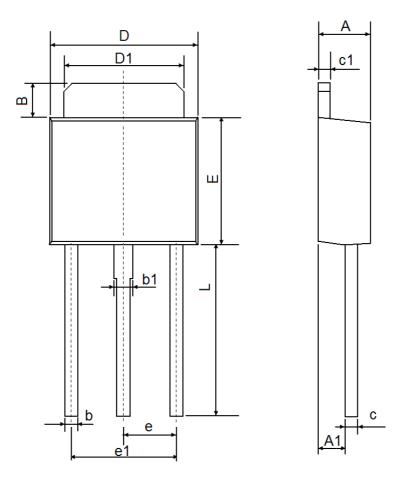
3) Unclamped Inductive Switching Test Circuit & Waveforms







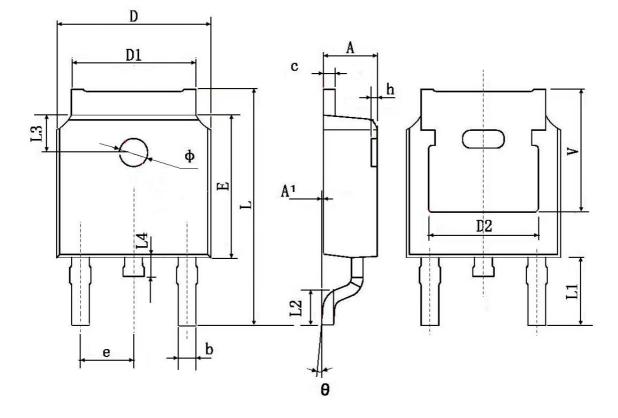
# **TO-251 Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	1.050	1.350	0.042	0.054
В	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
С	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091	TYP.
e1	4.500	4.700	0.177	0.185
L	7.500	7.900	0.295	0.311



# **TO-252 Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
С	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
е	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900	TYP.	0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600	TYP.	0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	





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